

09/915658

.DEF

C 25

PATENT

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

November 17, 2005 Carol L. Ross for

Date

Carolyn L. Ross

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants : Gundu M. Sabde
and Whonchee Lee

Attorney Docket No.: 500163.04

Patent No. : US 6,903,018 B2

Serial No. : 09/915,658

Issue Date : June 7, 2005

Filed : July 25, 2001

Title : METHODS AND APPARATUS FOR PLANARIZING MICROELECTRONIC
SUBSTRATE ASSEMBLIES

REQUEST FOR CERTIFICATE OF CORRECTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Certificate
NOV 30 2005
of Correction

Sir:

A Certificate of Correction under 35 U.S.C. § 254 is respectfully requested for the above-identified patent in order to correct Patent and Trademark Office errors made during the printing of the patent. The changes in the patent needed to correct the errors are as follows:

<u>Column, Line</u>	<u>Reads</u>	<u>Should Read</u>
Column 1, Line 11 Technical Field	Omitted	--The present invention relates to methods and apparatuses for planarizing microelectronic substrate assemblies and, more particularly, to mechanical and/or chemical-mechanical planarization of such substrate assemblies using non-abrasive planarizing solutions and fixed-abrasive polishing pads--

NOV 30 2005

Column 4, Line 60	"160 can be glycerol, polyethylene glycol polypropylene"	--160 can be glycerol, polyethylene glycol, polypropylene--
-------------------	----------------------------------------------------------------	-------------------------------------------------------------------

The above errors for which correction is requested under 35 U.S.C. § 254 were made in the printing of the patent. The errors are considered sufficiently important to justify the processing of a Certificate of Correction under 35 U.S.C. § 254. A Form PTO-1050, in duplicate, is enclosed herewith.

The Commissioner is hereby authorized to charge payment of any fees associated with this communication to Deposit Account No. 50-1266. A duplicate copy of this sheet is enclosed.

Favorable consideration of this Request is respectfully requested.

Respectfully submitted,

Date:

Nov. 17, 2005

By:

Edward W. Bulchis

Edward W. Bulchis, Reg. No. 26,847

Customer No. 27,076

Dorsey & Whitney LLP

1420 Fifth Avenue, Suite 3400

Seattle, WA 98101

(206) 903-8785

Attorney for Applicant(s)

EWB:clr

Enclosures:

Postcard

Form PTO-1050 (+ copy)

H:\IP\Clients\Micron Technology\100\500163.04\500163.04 req cert correct.doc

NOV 30 2005

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.



November 17, 2005 *ALA'L* *for*
 Carolyn L. Ross

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Gundu M. Sabde
 and Whonchee Lee

Attorney Docket No.: 500163.04

Patent No. : US 6,903,018 B2

Serial No. : 09/915,658

Issue Date : June 7, 2005

Filed : July 25, 2001

Title : METHODS AND APPARATUS FOR PLANARIZING MICROELECTRONIC
 SUBSTRATE ASSEMBLIES

REQUEST FOR CERTIFICATE OF CORRECTION

Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

Sir:

A Certificate of Correction under 35 U.S.C. § 254 is respectfully requested for the above-identified patent in order to correct Patent and Trademark Office errors made during the printing of the patent. The changes in the patent needed to correct the errors are as follows:

<u>Column, Line</u>	<u>Reads</u>	<u>Should Read</u>
Column 1, Line 11 Technical Field	Omitted	--The present invention relates to methods and apparatuses for planarizing microelectronic substrate assemblies and, more particularly, to mechanical and/or chemical-mechanical planarization of such substrate assemblies using non-abrasive planarizing solutions and fixed-abrasive polishing pads--

NOV 30 2005

Column 4, Line 60	"160 can be glycerol, polyethylene glycol polypropylene"	--160 can be glycerol, polyethylene glycol, polypropylene--
-------------------	----------------------------------------------------------------	-------------------------------------------------------------------

The above errors for which correction is requested under 35 U.S.C. § 254 were made in the printing of the patent. The errors are considered sufficiently important to justify the processing of a Certificate of Correction under 35 U.S.C. § 254. A Form PTO-1050, in duplicate, is enclosed herewith.

The Commissioner is hereby authorized to charge payment of any fees associated with this communication to Deposit Account No. 50-1266. A duplicate copy of this sheet is enclosed.

Favorable consideration of this Request is respectfully requested.

Respectfully submitted,

Date:

Nov. 17, 2005

By:

Edward W. Bulchis

Edward W. Bulchis, Reg. No. 26,847

Customer No. 27,076

Dorsey & Whitney LLP

1420 Fifth Avenue, Suite 3400

Seattle, WA 98101

(206) 903-8785

Attorney for Applicant(s)

EWB:clr

Enclosures:

Postcard

Form PTO-1050 (+ copy)

H:\IP\Clients\Micron Technology\100\500163.04\500163.04 req cert correct.doc

NOV 30 2005

**UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION**

PATENT NO. : US 6,903,018 B2
DATED : June 7, 2005
INVENTOR(S) : Gundu M. Sabde and Whonchee Lee

It is certified that error appears in the above identified patent and that said Letters Patent is hereby corrected as shown below:

<u>Column, Line</u>	<u>Reads</u>	<u>Should Read</u>
Column 1, Line 11, Technical Field	Omitted	--The present invention relates to methods and apparatuses for planarizing microelectronic substrate assemblies and, more particularly, to mechanical and/or chemical-mechanical planarization of such substrate assemblies using non-abrasive planarizing solutions and fixed-abrasive polishing pads--
Column 4, Line 60	"160 can be glycerol, polyethylene glycol polypropylene"	--160 can be glycerol, polyethylene glycol, polypropylene--

MAILING ADDRESS OF SENDER:

DORSEY & WHITNEY LLP
1420 Fifth Avenue, Suite 3400
Seattle, Washington 98101

Patent No. US 6,903,018 B2

No. add'l. copies
@ .30 per page



FORM PTO-1050 (REV. 3-82)

h:\ip\clients\micron technology\100\500163.04\500163.04 pto 1050.doc

NOV 3 0 2005

**UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION**

PATENT NO. : US 6,903,018 B2
DATED : June 7, 2005
INVENTOR(S) : Gundu M. Sabde and Whonchee Lee

It is certified that error appears in the above identified patent and that said Letters Patent is hereby corrected as shown below:

<u>Column, Line</u>	<u>Reads</u>	<u>Should Read</u>
Column 1, Line 11, Technical Field	Omitted	--The present invention relates to methods and apparatuses for planarizing microelectronic substrate assemblies and, more particularly, to mechanical and/or chemical-mechanical planarization of such substrate assemblies using non-abrasive planarizing solutions and fixed-abrasive polishing pads--
Column 4, Line 60	"160 can be glycerol, polyethylene glycol polypropylene"	--160 can be glycerol, polyethylene glycol, polypropylene--

MAILING ADDRESS OF SENDER:

DORSEY & WHITNEY LLP
1420 Fifth Avenue, Suite 3400
Seattle, Washington 98101

Patent No. US 6,903,018 B2

No. add'l. copies
@ .30 per page



FORM PTO-1050 (REV. 3-82)

h:\ip\clients\micron technology\100\500163.04\500163.04 pto 1050.doc

NOV 30 2005